

E 13/7/4 (EF 12.6) Cores and accessories

Series/Type: B66305, B66202, B66306, B66414

Date: May 2017

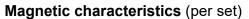
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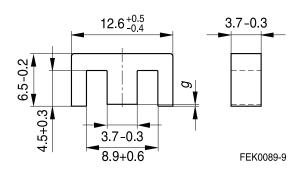


Core B66305

- To IEC 62317-8
- For miniature transformers
- Available with SMD coil former
- E cores with high permeability for common-mode chokes and broadband applications
- Delivery mode: single units



 $\Sigma I/A = 2.39 \text{ mm}^{-1}$ = 29.6 mm $= 12.4 \text{ mm}^2$ $A_{min} = 12.2 \text{ mm}^2$ $V_e = 367 \text{ mm}^3$



Approx. weight 2 g/set

Ungapped

Material	A _L value nH	μ_{e}	P _V W/set	Ordering code
N30	1000 +30/–20%	1900		B66305G0000X130
T65	1300 ±30%	2470		B66305G0000X165
T65	1900 ±30%	3610		B66305F0000X165
T46	3600 ±30%	6839		B66305F0000X146
N27	800 +30/–20%	1510	< 0.40 (200 mT, 100 kHz, 100 °C)	B66305G0000X127
N87	850 +30/–20%	1620	< 0.20 (200 mT, 100 kHz, 100 °C)	B66305G0000X187

Gapped (A_I values/air gaps examples)

Material	g mm	A _L value approx. nH	μ_{e}	Ordering code
N27	0.04 ±0.01	250	454	B66305G0040X127
	0.5 ±0.05	45	85	B66305G0500X127
N87	0.04 ±0.01	280	530	B66305G0040X187
	0.13 ±0.02	112	215	B66305G0130X187
	0.30 ±0.02	64	122	B66305G0300X187

The A_L value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

Other A_I values/air gaps and materials available on request — see Processing remarks on page 8.



Core B66305

Calculation factors (for formulas, see "E cores: general information")

Material	Relationship air gap – A _L v		Calculation of saturation current			
K1 (25 °C) K2 (25 °C)		K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N27	28.4	-0.676	36.5	-0.847	33.2	-0.865
N87	28.4	-0.676	37.5	-0.796	32.1	-0.873

Validity range: K1, K2: 0.03 mm < s < 1.00 mm

K3, K4: 30 nH < A_L < 260 nH



Accessories B66202

Coil former (magnetic axis horizontal or vertical)

Material: GFR polyterephthalate (UL 94 V-0, insulation class to IEC 60085:

F ≙ max. operating temperature 155 °C), color code black Valox 420-SE0® [E207780 (M)], SABIC JAPAN L L C

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 350 °C, 3.5 s

Winding: see Processing notes, 2.1

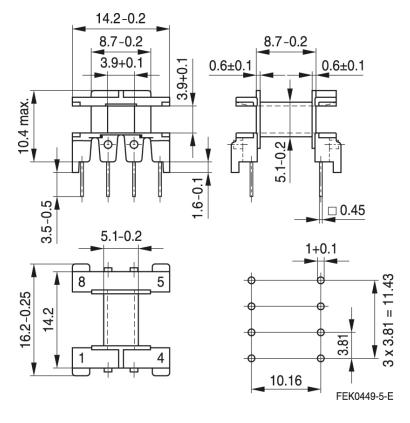
Pins: Squared pins

Yoke

Material: Stainless spring steel (0.2 mm)

Coil former					Ordering code	
Version	Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Pins	
Horizontal	1	11.6	27.2	80.6	8	B66202B1108T001
Vertical	1	11.6	27.2	80.6	6	B66202B1106T001
Yoke (ordering code per piece, 2 are required)					B66202A2010X000	

Horizontal version

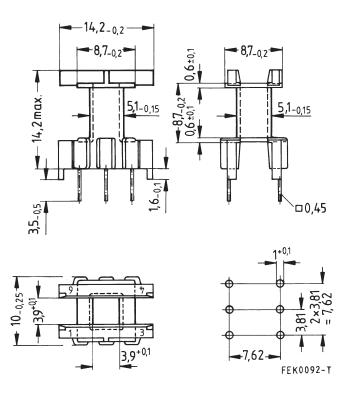


Hole arrangement View in mounting direction



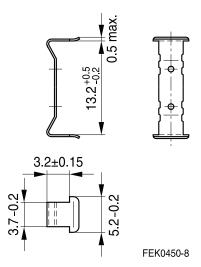
Accessories B66202

Vertical version



Hole arrangement View in mounting direction

Yoke





Accessories B66306



SMD coil former with gullwing terminals

Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085:

F ≙ max. operating temperature 155 °C), color code black Vectra E 130i [E106764 (M)], POLYPLASTICS CO LTD

Vectra E 130i [E83005 (M)], CELANESE INTERNATIONAL CORP.

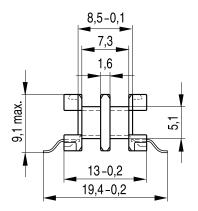
Solderability: to IEC 60068-2-58, test Td, method 6 (Group 3): 245 °C, 3 s

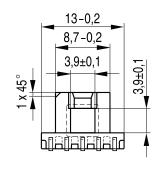
Resistance to soldering heat: to IEC 60068-2-58, test Td, method 6 (Group 3): 255 °C, 10 s

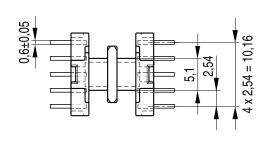
permissible soldering temperature for wire-wrap connection on coil former: 400 °C, 1 s

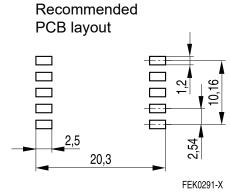
Winding: see Processing notes, 2.1

Sections	A _N mm ²	I _N mm	A_R value $\mu\Omega$	Terminals	Ordering code
1	13.0	27	71	10	B66306C1010T001
2	10.2	27	91	10	B66306C1010T002











Accessories B66414

Cover plate

Material: GFR liquid crystal polymer (UL 94 V-0, insulation class to IEC 60085:

F

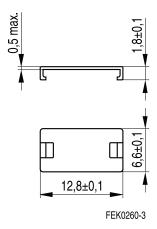
max. operating temperature 155 °C), color code black

Sumika Super E4008® [E54705 (M)], SUMITOMO CHEMICAL CO LTD

■ For stamping and for improved processing on assembly machines

■ See under SMD coil former for material and resistance to soldering heat

	Ordering code
Cover plate	B66414A7000X000





Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

EPCOS ferrite accessories have been designed and evaluated only in combination with EPCOS ferrite cores. EPCOS explicitly points out that EPCOS ferrite accessories or EPCOS ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

EPCOS assumes no warranty or reliability for the combination of EPCOS ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability
 problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

8



Cautions and warnings

Display of ordering codes for EPCOS products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_L	Inductance factor; A _L = L/N ²	nH
A_{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A_N	Winding cross section	mm ²
A _R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m², mT
ΔΒ	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
Δ B	Peak value of flux density deviation	Vs/m², mT
B_{DC}	DC magnetic flux density	Vs/m ² , mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E _a	Activation energy	J
f	Frequency	s ^{−1} , Hz
f _{cutoff}	Cut-off frequency	s−1, Hz
f _{max}	Upper frequency limit	s ^{−1} , Hz
f _{min}	Lower frequency limit	s−1, Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ^{−6} cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
l	RMS value of current	Α
I_{DC}	Direct current	Α
Î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

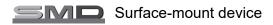
Symbol	Meaning	Unit
Δ L/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L _H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P _V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = $\omega L/R_s$ = 1/tan δ_l)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R _h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R _i	Internal resistance	Ω
R _p	Parallel loss resistance of a core	Ω
R _s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R _V	Effective loss resistance of a core	Ω
s	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	K
T _C	Curie temperature	°C
t	Time	s
t_v	Pulse duty factor	
tan δ	Loss factor	
$tan \delta_l$	Loss factor of coil	
$tan \delta_r$	(Residual) loss factor at H \rightarrow 0	
$\tan \delta_{\rm e}$	Relative loss factor	
$\tan \delta_{\rm h}$	Hysteresis loss factor	
$\tan \delta_{\rm h}$ tan $\delta/\mu_{\rm i}$	Relative loss factor of material at H \rightarrow 0	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
v _e Z	Complex impedance	Ω
	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e/A_e)$	Ω/mm
Z_n	INOTHIALIZED IMPEDIATION LIN - X C (Ie/Ae)	22/11111



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
ε_{r}	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η _B	Hysteresis material constant	mT-1
η _i	Hysteresis core constant	$A^{-1}H^{-1/2}$
λ_{s}	Magnetostriction at saturation magnetization	
ı	Relative complex permeability	
$\mathfrak{1}_0$	Magnetic field constant	Vs/Am
la	Relative amplitude permeability	
l _{app}	Relative apparent permeability	
le	Relative effective permeability	
l _i	Relative initial permeability	
ι _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
ւ _թ "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
ι_{r}	Relative permeability	
ι_{rev}	Relative reversible permeability	
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
ι_{tot}	Relative total permeability	
	derived from the static magnetization curve	
)	Resistivity	Ω m ⁻¹
ΣΙ/Α	Magnetic form factor	mm ⁻¹
r _{Cu}	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	S
ω	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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